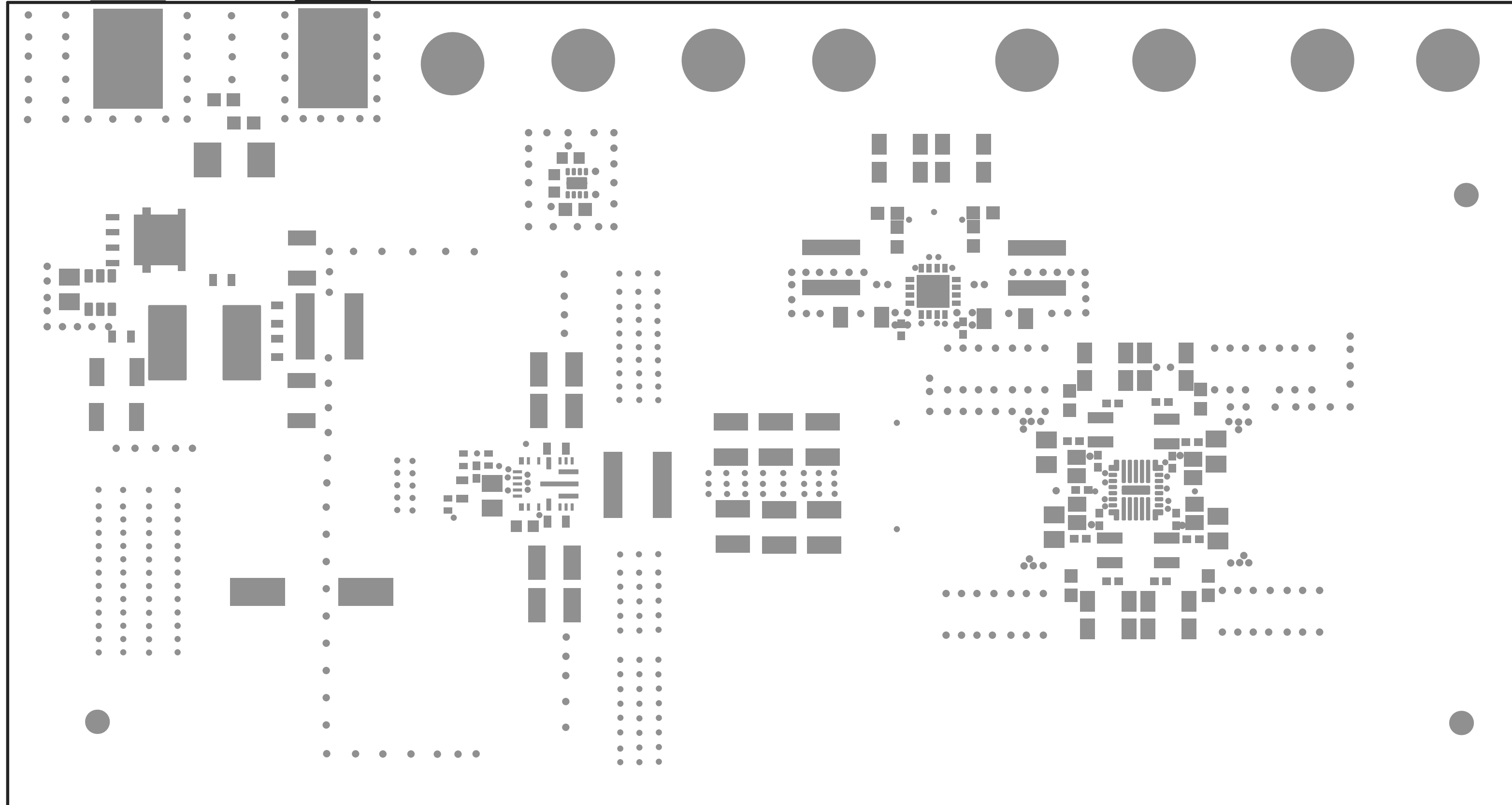
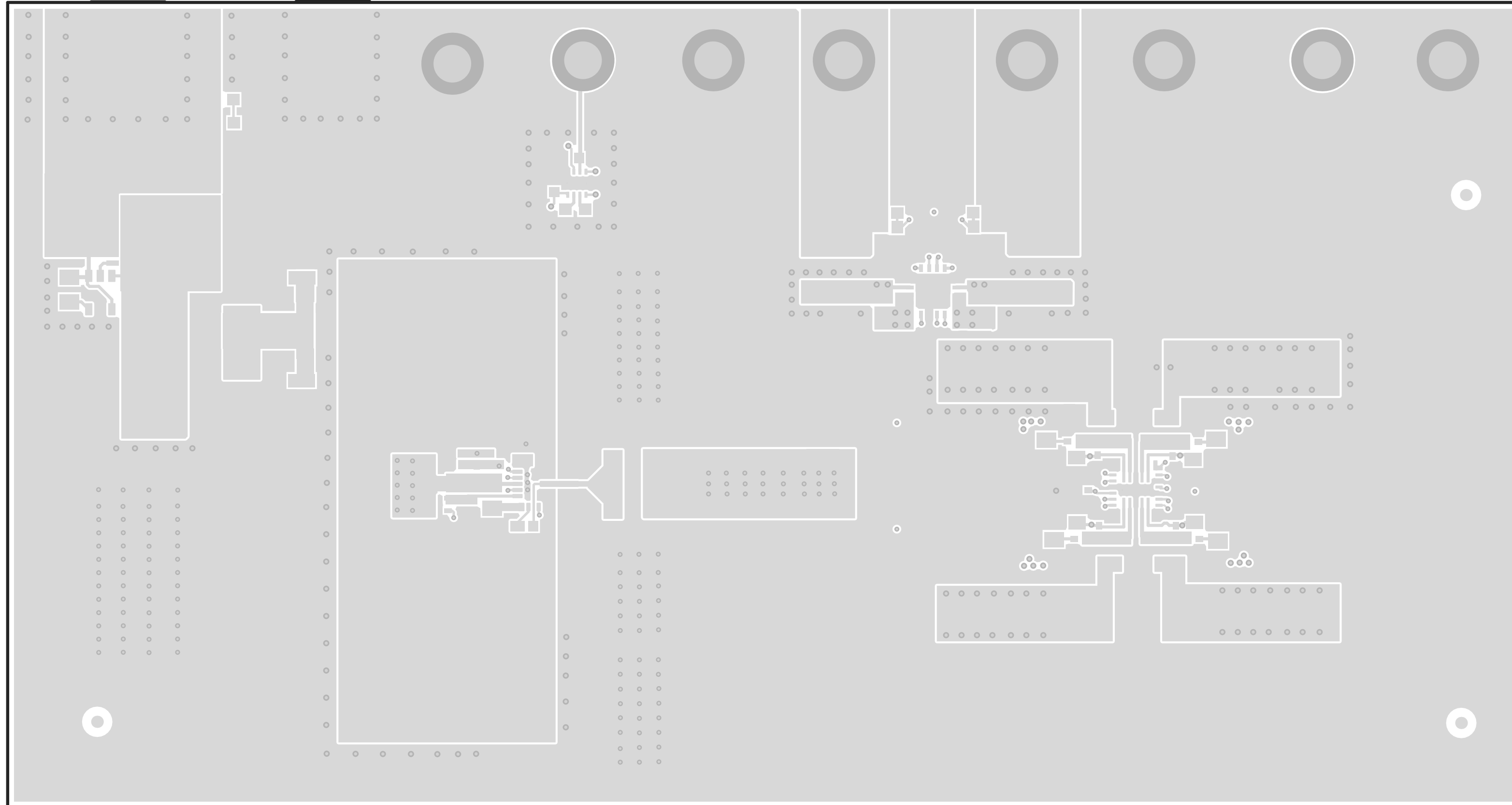


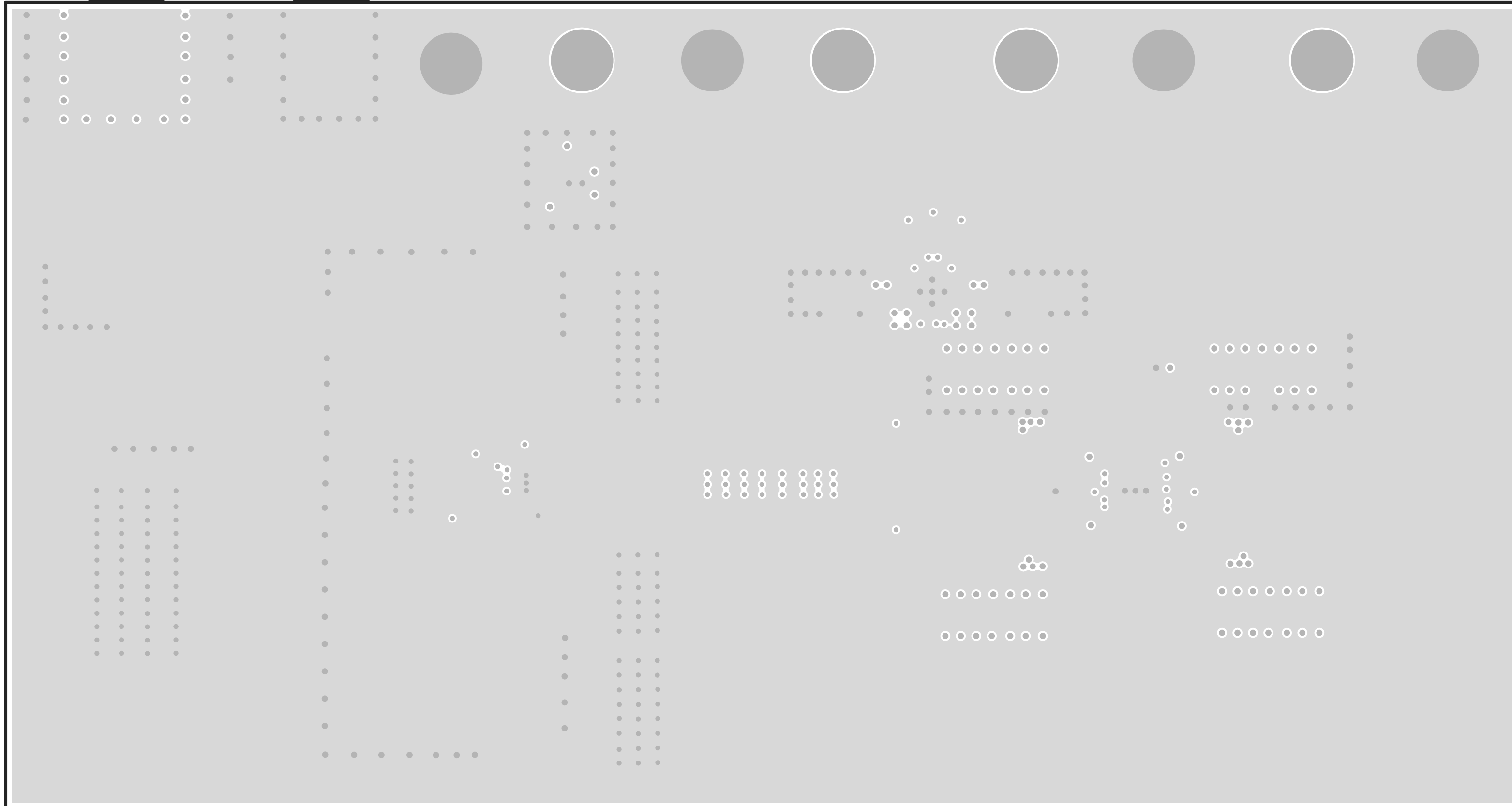
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Top Overlay	GENERATED : 11/14/2017 10:39:28 AM		TEXAS INSTRUMENTS



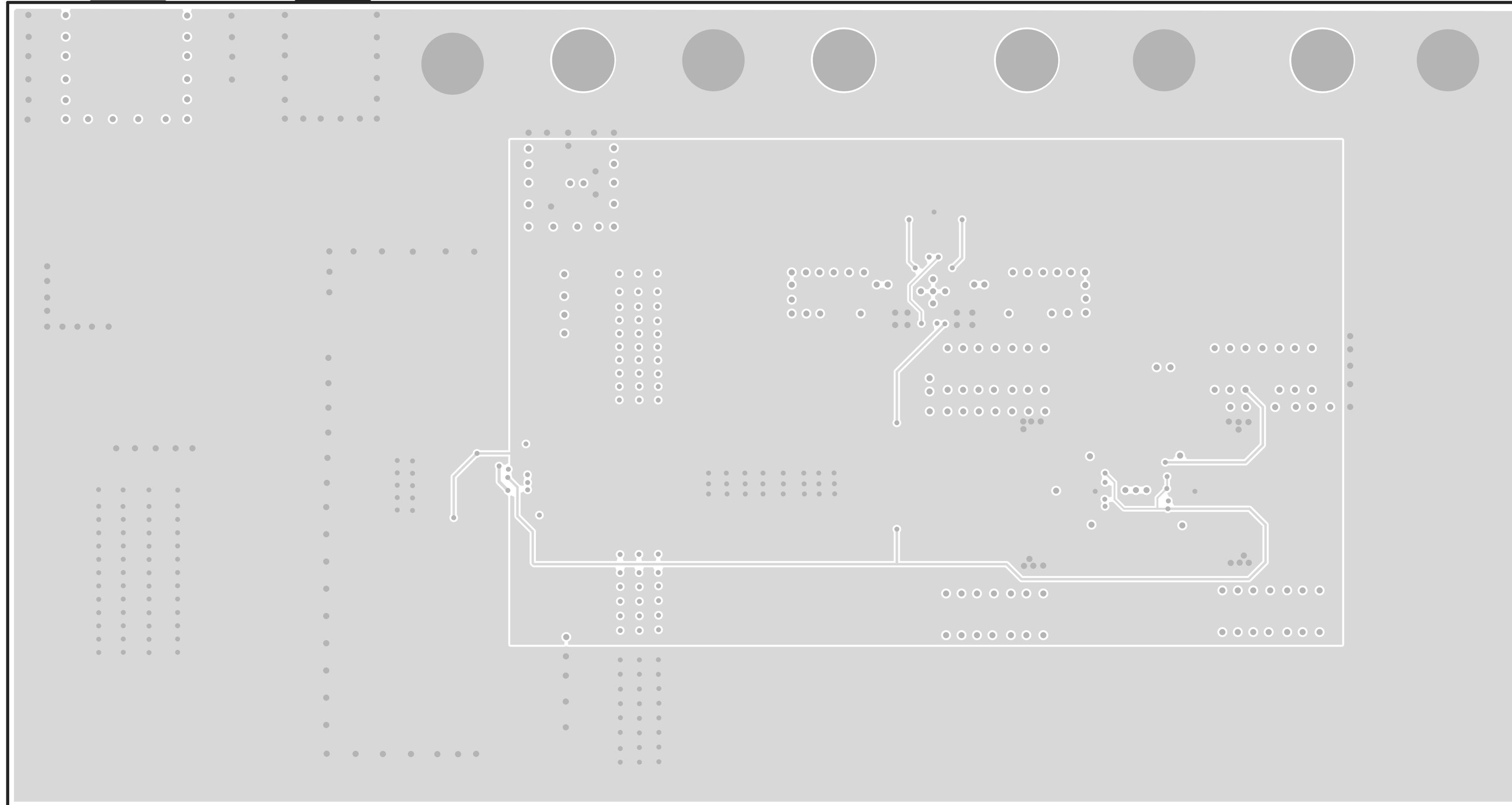
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Top Solder Mask	GENERATED : 11/14/2017 10:39:28 AM	TEXAS INSTRUMENTS	



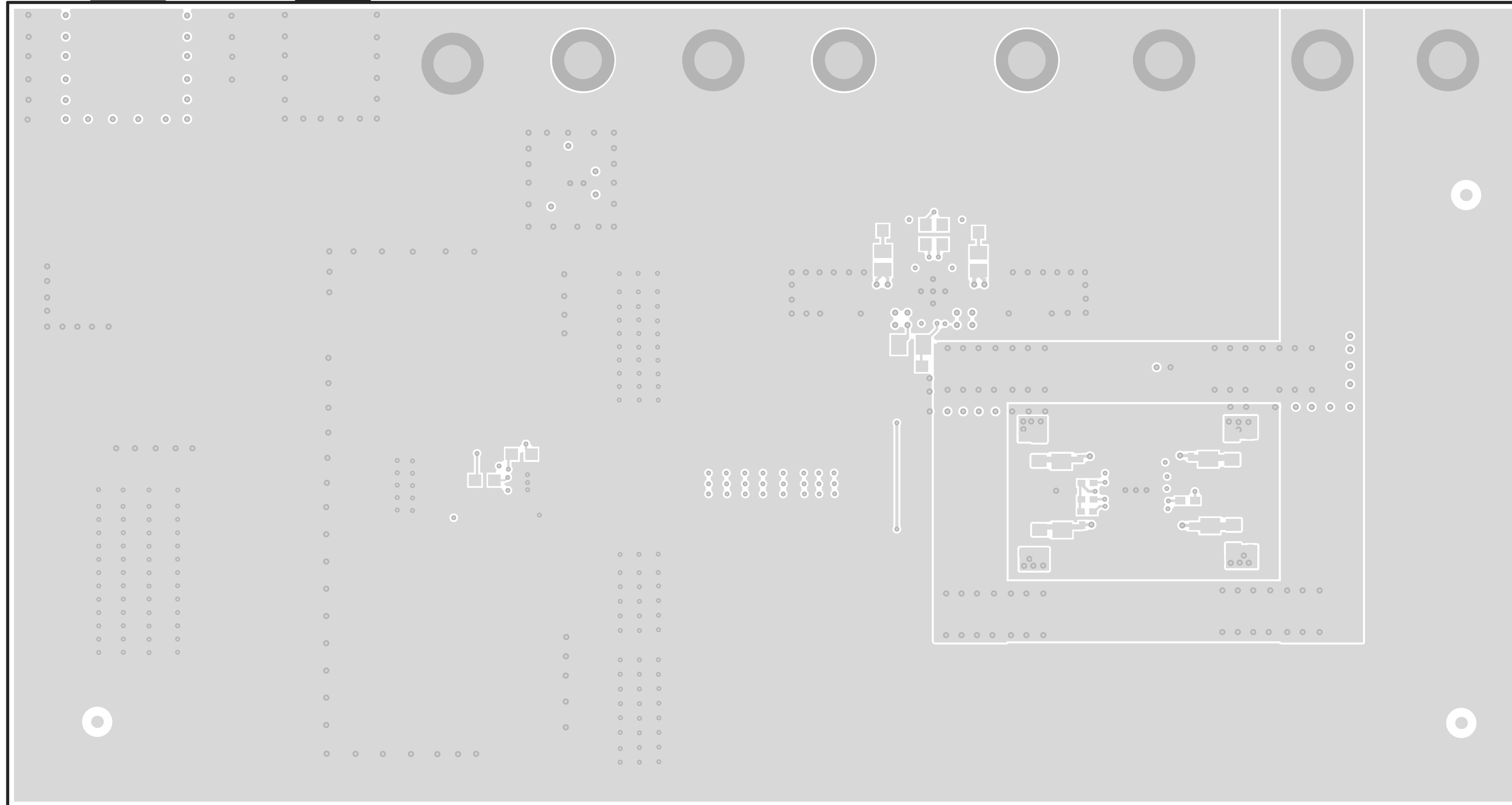
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Top Layer	GENERATED : 11/14/2017 10:39:28 AM	TEXAS INSTRUMENTS	



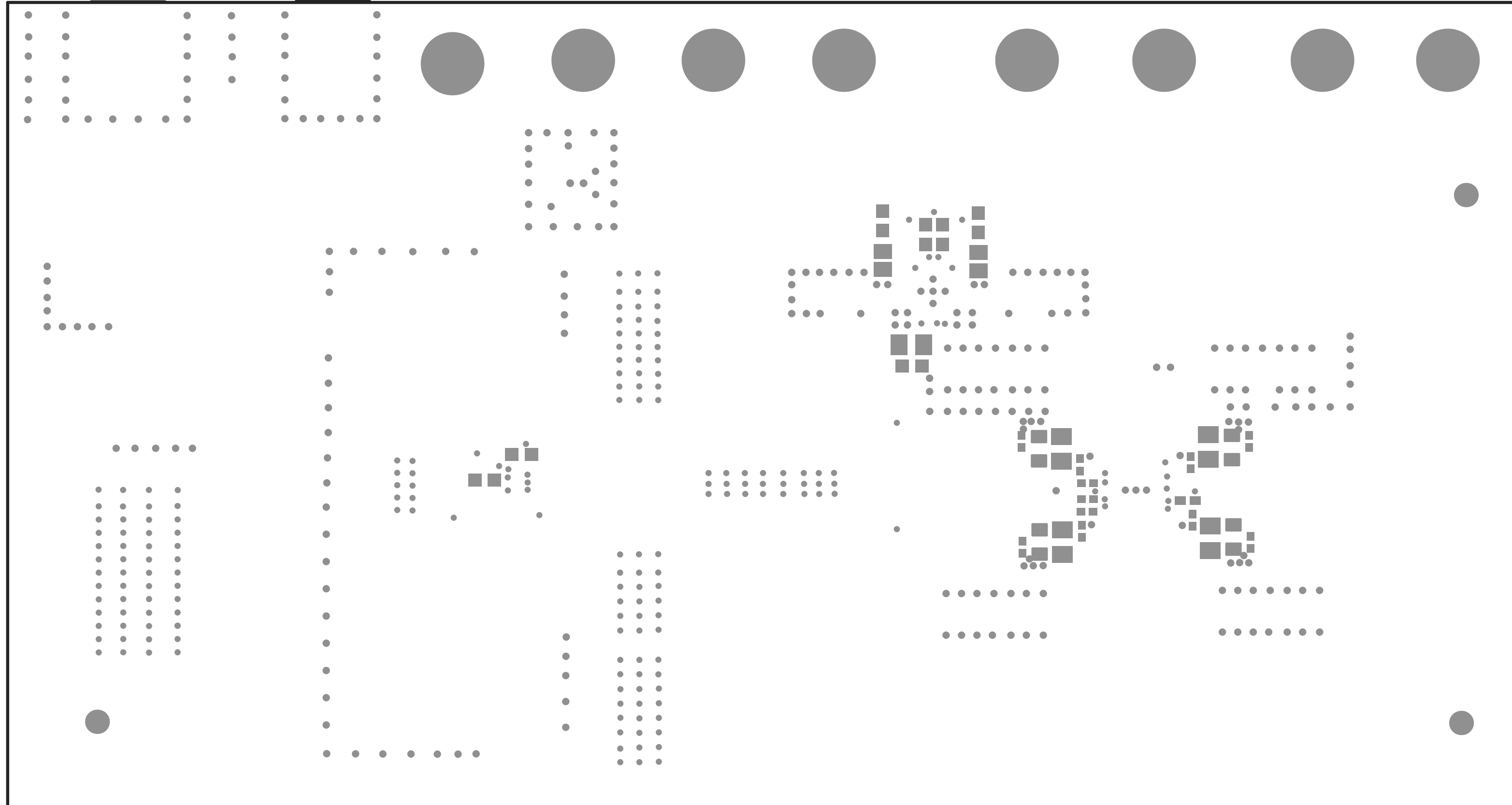
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Signal Layer 1	GENERATED : 11/14/2017 10:39:28 AM		TEXAS INSTRUMENTS



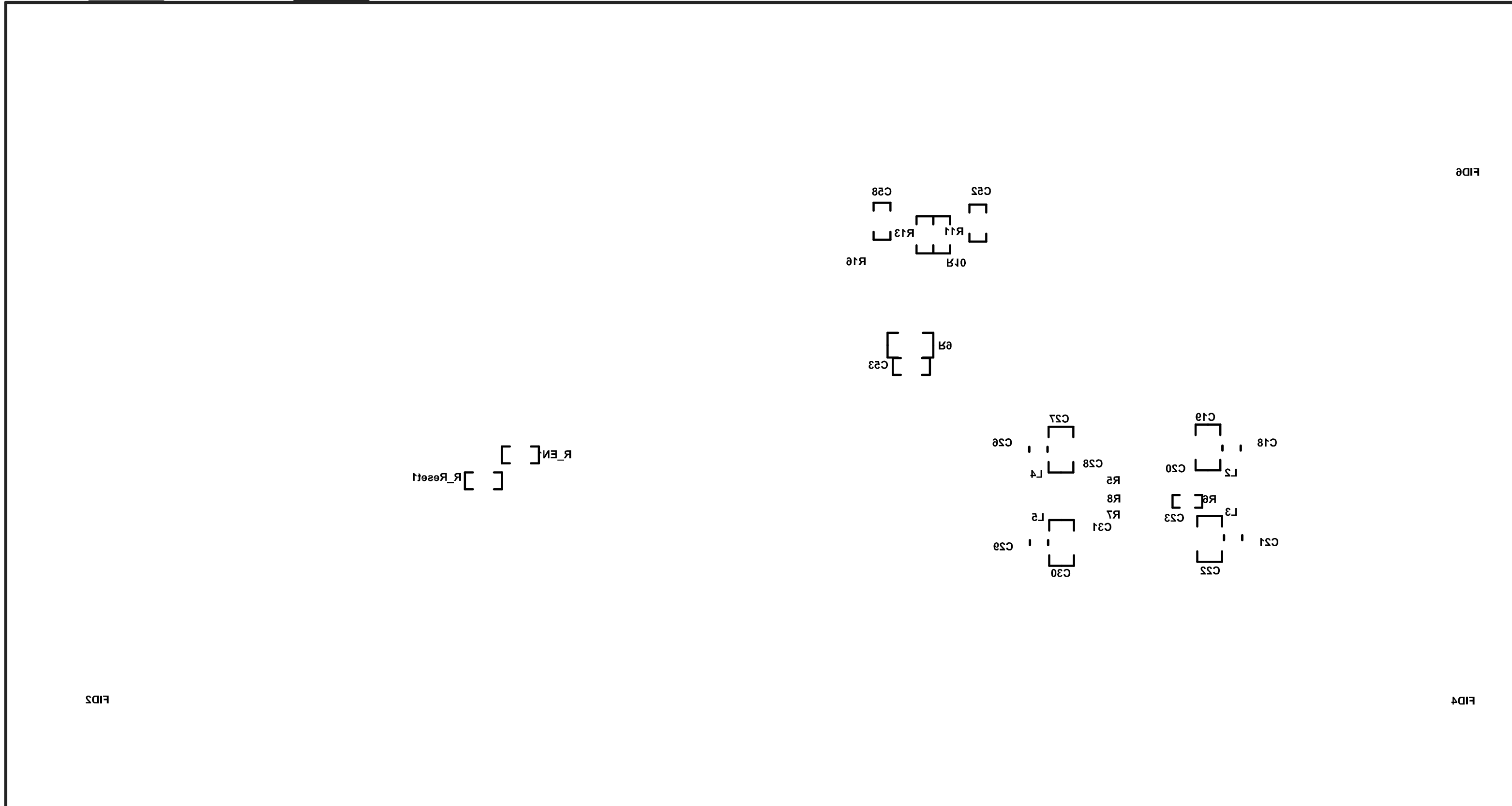
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Signal Layer 2	GENERATED : 11/14/2017 10:39:29 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Bottom Layer	GENERATED : 11/14/2017 10:39:29 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/14/2017 10:39:29 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01524	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01524		
PLOT NAME = Bottom Overlay	GENERATED : 11/14/2017 10:39:29 AM		TEXAS INSTRUMENTS



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